

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Field Device Integration (FDI)<sup>®</sup> –  
Part 103-4: PROFINET**

**(standards.iteh.ai)**

**Intégration des appareils de terrain (FDI)<sup>®</sup> –  
Partie 103-4: PROFINET**

IEC 62769-103-4:2023

<https://standards.iteh.ai/catalog/standards/sist/df465248-a634-418d-90ef-5144abc5303a/iec-62769-103-4-2023>



**THIS PUBLICATION IS COPYRIGHT PROTECTED**  
**Copyright © 2023 IEC, Geneva, Switzerland**

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Secretariat  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

#### **About the IEC**

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

#### **About IEC publications**

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

#### **IEC publications search - [webstore.iec.ch/advsearchform](http://webstore.iec.ch/advsearchform)**

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee, ...). It also gives information on projects, replaced and withdrawn publications.

#### **IEC Products & Services Portal - [products.iec.ch](http://products.iec.ch)**

Discover our powerful search engine and read freely all the publications previews. With a subscription you will always have access to up to date content tailored to your needs.

#### **IEC Just Published - [webstore.iec.ch/justpublished](http://webstore.iec.ch/justpublished)**

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

#### **Electropedia - [www.electropedia.org](http://www.electropedia.org)**

The world's leading online dictionary on electrotechnology, containing more than 22 300 terminological entries in English and French, with equivalent terms in 19 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

#### **IEC Customer Service Centre - [webstore.iec.ch/csc](http://webstore.iec.ch/csc)**

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: [sales@iec.ch](mailto:sales@iec.ch).

---

#### **A propos de l'IEC**

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

#### **A propos des publications IEC**

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

#### **Recherche de publications IEC -**

##### **[webstore.iec.ch/advsearchform](http://webstore.iec.ch/advsearchform)**

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études, ...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

Découvrez notre puissant moteur de recherche et consultez gratuitement tous les aperçus des publications. Avec un abonnement, vous aurez toujours accès à un contenu à jour adapté à vos besoins.

#### **IEC Just Published - [webstore.iec.ch/justpublished](http://webstore.iec.ch/justpublished)**

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et une fois par mois par email.

#### **Electropedia - [www.electropedia.org](http://www.electropedia.org)**

Le premier dictionnaire d'électrotechnologie en ligne au monde, avec plus de 22 300 articles terminologiques en anglais et en français, ainsi que les termes équivalents dans 19 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

#### **Service Clients - [webstore.iec.ch/csc](http://webstore.iec.ch/csc)**

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: [sales@iec.ch](mailto:sales@iec.ch).

#### **IEC Products & Services Portal - [products.iec.ch](http://products.iec.ch)**



IEC 62769-103-4

Edition 3.0 2023-04

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



Field Device Integration (FDI)<sup>®</sup> –  
Part 103-4: PROFINET

Intégration des appareils de terrain (FDI)<sup>®</sup> –  
Partie 103-4: PROFINET

[IEC 62769-103-4:2023](#)

<https://standards.iteh.ai/catalog/standards/sist/df465248-a634-418d-90ef-5144abc5303a/iec-62769-103-4-2023>

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

COMMISSION  
ELECTROTECHNIQUE  
INTERNATIONALE

ICS 25.040.40; 35.100.05

ISBN 978-2-8322-6821-6

**Warning! Make sure that you obtained this publication from an authorized distributor.  
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

## CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references .....	6
3 Terms, definitions, abbreviated terms and acronyms .....	7
3.1 Terms and definitions.....	7
3.2 Abbreviated terms and acronyms .....	7
4 Conventions .....	7
4.1 EDDL syntax.....	7
4.2 XML syntax.....	7
4.3 Capitalizations .....	7
5 Profile for PROFINET .....	8
5.1 General.....	8
5.2 Catalog profile .....	8
5.2.1 Protocol support file.....	8
5.2.2 CommunicationProfile definition.....	9
5.2.3 Profile device.....	9
5.2.4 Protocol version information .....	9
5.3 Associating a Package with a device.....	10
5.3.1 Device type identification mapping.....	10
5.3.2 Device type revision mapping .....	11
5.4 Information Model mapping.....	12
5.4.1 ProtocolType definition .....	12
5.4.2 DeviceType mapping .....	13
5.4.3 FunctionalGroup identification definition .....	13
5.5 Topology elements.....	14
5.5.1 ConnectionPoint definition .....	14
5.5.2 Communication Device definition .....	15
5.5.3 Communication service provider definition .....	16
5.5.4 Network definition .....	17
5.6 Methods.....	17
5.6.1 Methods for FDI <sup>®</sup> Communication Servers .....	17
5.6.2 Methods for Gateways .....	21
Annex A (normative) Topology scan schema.....	29
A.1 General.....	29
A.2 Target Namespace.....	29
A.3 Network .....	29
A.4 ProfinetNetworkT .....	29
A.5 ProfinetConnectionPointT .....	30
A.6 ProfinetIdentificationT .....	30
A.7 MACT .....	32
A.8 IPv4T.....	32
A.9 IPv6T.....	32
A.10 DNSNameT.....	32
A.11 Hex4DigitT.....	32
Annex B (normative) Transfer service parameters.....	33
B.1 General.....	33

B.2	Target Namespace.....	33
B.3	sendData .....	33
B.4	receiveData .....	33
B.5	TransferSendDataT.....	33
B.6	TransferResultDataT.....	34
B.7	OperationT.....	35
Annex C (informative)	Mapping to PA DIM .....	36
C.1	General.....	36
C.2	Mapping table .....	36
Bibliography	.....	37
Figure 1	– Version mapping problem.....	11
Table 1	– ProtocolSupportFile for FDI® Device Packages.....	9
Table 2	– ProtocolSupportFile for FDI® Communication Packages .....	9
Table 3	– Catalog values for profile devices.....	9
Table 4	– Version mapping examples.....	10
Table 5	– Device identification information mapping.....	11
Table 6	– Protocol type Profinet_IO .....	12
Table 7	– DeviceType Property mapping.....	13
Table 8	– PROFINET identification type definition.....	13
Table 9	– ConnectionPoint type for Profinet_IO .....	14
Table 10	– Method Connect arguments.....	18
Table 11	– Method Disconnect arguments.....	19
Table 12	– Method Transfer arguments.....	20
Table 13	– Method SetAddress arguments.....	21
Table 14	– Method Connect arguments.....	23
Table 15	– Method Transfer arguments.....	24
Table 16	– Method SetAddress arguments.....	26
Table A.1	– Elements of ProfinetNetworkT .....	29
Table A.2	– Attributes of ProfinetConnectionPointT .....	30
Table A.3	– Elements of ProfinetConnectionPointT .....	30
Table A.4	– Attributes of ProfinetIdentificationT .....	31
Table B.1	– Attributes of TransferSendDataT .....	34
Table B.2	– Attributes of TransferResultDataT .....	34
Table C.1	– Mapping from PN standard parameters to PA DIM .....	36

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**FIELD DEVICE INTEGRATION (FDI®) –****Part 103-4: PROFINET**

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

IEC 62769-103-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2020. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DeviceType to ProfinetIdentificationT;
- b) added namespace to Annex A and Annex B;
- c) added mapping rule for Device type when running in profile mode;
- d) replaced GSD file with GSDML file, detailing of device type mapping;
- e) added mapping to PA DIM.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/863/CDV	65E/920/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/standardsdev/publications](http://www.iec.ch/standardsdev/publications).

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI)*<sup>®</sup>, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

<https://standards.iteh.ai/catalog/standards/sist/df465248-a634-418d-90ef-5144abc5303a/iec-62769-103-4-2023>

**IMPORTANT – The "colour inside" logo on the cover page of this document indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.**

# FIELD DEVICE INTEGRATION (FDI®) –

## Part 103-4: PROFINET

### 1 Scope

This part of IEC 62769 specifies an FDI®<sup>1</sup> profile of IEC 62769 for IEC 61784-2\_CP 3/4, IEC 61784-2\_CP3/5 and IEC 61784-2\_CP3/6 (PROFINET<sup>2</sup>).

### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158-5-10, *Industrial communication networks – Fieldbus specifications – Part 5-10: Application layer service definition – Type 10 elements*

IEC 61784-2, *Industrial communication networks – Profiles – Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3*

IEC 61804 (all parts), *Devices and integration in enterprise systems – Function blocks (FB) for process control and electronic device description language (EDDL)*

IEC 62541-100:2015, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-2, *Field device integration (FDI®) – Part 2: Client*

IEC 62769-4, *Field device integration (FDI®) – Part 4: FDI® Packages*

IEC 62769-5, *Field device integration (FDI®) – Part 5: Information Model*

IEC 62769-6, *Field device integration (FDI®) – Part 6: Technology Mapping*

IEC 62769-7, *Field device integration (FDI®) – Part 7: Communication devices*

PI Order No.: 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – Volume 1: GSD, V5.1, July 2008: GSD*; available at <[www.PROFIBUS.com](http://www.PROFIBUS.com)>

---

<sup>1</sup> FDI is a registered trademark of the non-profit organization Fieldbus Foundation, Inc. This information is given for the convenience of users of this document and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

<sup>2</sup> PROFINET is the trade name of the non-profit consortium PROFIBUS & PROFINET International. This information is given for the convenience of users of this technical report and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.



PI Order No.: 2.352:2014, *GSDML Specification for PROFINET IO*; available at [www.PROFIBUS.com](http://www.PROFIBUS.com)

### 3 Terms, definitions, abbreviated terms and acronyms

#### 3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61158-5-10, IEC 61784-2, IEC 61804 (all parts), IEC 62541-100, IEC 62769-2, IEC 62769-4, IEC 62769-5, IEC 62769-6, IEC 62769-7 and PI Order No.: 2.352:2014 apply.

ISO and IEC maintain terminology databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

#### 3.2 Abbreviated terms and acronyms

For the purposes of this document, the following abbreviated terms and acronyms apply:

DCP	Discovery and basic configuration protocol (see IEC 61158-5-10)
DNS	Domain name system
EDD	Electronic Device Description
EDDL	Electronic Device Description Language (see IEC 61804 (all parts))
GSD	General station description (see PI Order No.: 2.122:2008)
GSDML	GSD markup language (see PI Order No.: 2.352:2014)
IP	Internet protocol (IETF RFC 791)
UIP	User Interface plug-in
UUID	Universal unique identifier (see ISO/IEC 11578)
XML	Extensible markup language (see REC-xml-20081126)

### 4 Conventions

#### 4.1 EDDL syntax

This document specifies content for the EDD component that is part of FDI<sup>®</sup> Communication Packages. The specification content using EDDL syntax uses the font Courier New. The EDDL syntax is used for method signature, variable, data structure and component declarations.

#### 4.2 XML syntax

XML syntax examples use the font Courier New. The XML syntax is used to describe XML document schema.

Example: `<xs:simpleType name="ExampleType">`

#### 4.3 Capitalizations

The IEC 62769 series uses capitalized terms to emphasize that these terms have an FDI<sup>®</sup> specific meaning.

Some of these terms using an acronym as a prefix for example

- FDI<sup>®</sup> Client, or
- FDI<sup>®</sup> Server.

Some of these terms are compound terms such as:

- Communication Servers, or
- Profile for Package.

Parameter names or attributes are concatenated to a single term, where the original terms starting in this term with a capital letter such as:

- ProtocolSupportFile, or
- ProtocolType.

Parameter names or attributes can also be constructed by using an underscore character to concatenate two or more terms such as:

- PROFILE\_ID, or
- Profinet\_PA\_Network

## 5 Profile for PROFINET

### 5.1 General

This profile document to the FDI<sup>®</sup> specification in IEC 62769 specifies the protocol specifics needed for FDI<sup>®</sup> Packages describing Communication Servers, Gateways and Devices.

For Communication Servers this document defines also protocol specifics as these need to be considered in the Communication Servers hosted Information Model.

Annex B defines the XML schema for Direct Access Services. Annex C provides an overview of mapping PROFIBUS standard parameters to PA DIM.

### 5.2 Catalog profile

#### 5.2.1 Protocol support file

##### 5.2.1.1 FDI<sup>®</sup> Device Package

A GSDML file is a mandatory Attachment for FDI<sup>®</sup> Device Packages representing PROFINET IO devices.

Protocol specific attachments are mentioned in the Package Catalog as defined in IEC 62769-5. A communication feature list mark-up language (GSDML) file according to PI Order No.: 2.352:2014 is a mandatory attachment for FDI<sup>®</sup> Device Packages representing PROFINET devices. Table 1 specifies the parameters of ProtocolSupportFile in the FDI<sup>®</sup> Device Package.

**Table 1 – ProtocolSupportFile for FDI® Device Packages**

Parameter	Description
Content Type	text/xml
Root Namespace	Empty
Source Relationship	<a href="http://fdi-cooperation.com/2010/relationship/attachment-protocol">http://fdi-cooperation.com/2010/relationship/attachment-protocol</a>
Filename	According to PI Order No.: 2.352:2014.

### 5.2.1.2 FDI® Communication Package

A GSDML file as specified in ISO 15745-4:2003,/AMD1, is an optional attachment for FDI® Communication Packages representing PROFINET IO devices. Table 2 specifies the parameters of ProtocolSupportFile for FDI® Communication Packages.

**Table 2 – ProtocolSupportFile for FDI® Communication Packages**

Parameter	Description
Content Type	text/xml
Root Namespace	Empty
Source Relationship	<a href="http://fdi-cooperation.com/2010/relationship/attachment-protocol">http://fdi-cooperation.com/2010/relationship/attachment-protocol</a>
Filename	According to PI Order No.: 2.352:2014

### 5.2.2 CommunicationProfile definition

IEC 62769-4 defines a CommunicationProfileT string for the Catalog XML schema. The PROFINET specific value shall be "profinet\_io".

### 5.2.3 Profile device

A Profile Package shall provide the catalog values for profile devices, enabling the FDI® Server to leverage a generic device description, if a specific one is not available. The definitions in Table 3 focus on catalog content that is vendor independent.

**Table 3 – Catalog values for profile devices**

Element	Attribute	Content
PackageType	—	Profile
Manufacturer	—	Empty
DeviceModel	—	<p>Allowed profile identifier values (PROFILE_ID) are provided by PROFIBUS &amp; PROFINET International (PI). PI provides and maintains a XML file (Profile_ID_Table) containing the assignment of PROFILE_ID to profiles.</p> <p>It is available at &lt;<a href="http://www.profibus.com/IM/Profile_ID_Table.xml">http://www.profibus.com/IM/Profile_ID_Table.xml</a>&gt;</p> <p>The file can be downloaded by any engineering or service tool whenever it's connected to the Internet.</p> <p>NOTE More information is provided in PI Order No.: 3.502 (I&amp;M Profile) and related profile definitions referred therein.</p> <p>The string format shall be hexadecimal starting with 0x, e.g. '0x3D00'.</p>

### 5.2.4 Protocol version information

IEC 62769-4 defines an element type named InterfaceT for the Catalog XML schema. The element type InterfaceT contains an element named Version which is supposed to provide

version information about the applied communication protocol profile. The value has to follow the IEC 62769-4 defined version information schema defined in the element type VersionT. Table 4 describes how to apply the currently known protocol versions defined by the non-profit consortium PROFIBUS & PROFINET International. The general rule is to apply the value “0” for parts of the version information according to IEC 62769-4 that are not used in currently known protocol versions.

**Table 4 – Version mapping examples**

Protocol / Version	InterfaceT Version value
PROFINET Version 2.3	2.3.0
<p>NOTE 1 This Table is just an example since this document cannot foresee how future protocol versions will be defined.</p> <p>NOTE 2 The currently known PROFINET protocol revision information provides major and minor version information. Leading zeros are not considered in version value evaluation since only the actual decimal values are relevant.</p>	

**5.3 Associating a Package with a device**

**5.3.1 Device type identification mapping**

The purpose of a device type identification mapping is to enable FDI® host systems to compare the scan result against the topology representation in the Information Model. FDI® host systems shall also be enabled to determine the FDI® Device Package that fits for a device entry contained in the scan result. This will enable the user of an FDI® host system to synchronize the Information Model with the actual installation.

The communication server implemented scan service (defined in 5.6.1.7) provides a scan result through an XML document (schema defined in Annex A).

The Gateway implemented scan service (defined in 5.6.2.7) provides a scan result by means of the Information Model that contains data structures created from EDD content as specified in 5.6.2.7.

Common for both ways of presenting the scan result is that scan results contain device type identification and device instance identification.

FDI® host systems comparing the actual network topology configuration against the topology representation in the Information Model shall be enabled to handle the following situations:

- a) The physical Device instance identified at a specific device address is not logically present in the Information model (as Instance): Enable the FDI® Host system to find the appropriate FDI® Device package according to the device catalogue information.
- b) The physical Device instance identified by the device address is logically present in the Information Model (as Instance): Enable the FDI® Host system to compare the device type information presented in the scan result (see the identification in Clause A.6 and 5.6.2.7) and the device type specific information of the Instance present in the Information Model.

The FDI® Device package contains device type identification information that can be compared to the scan result based on the Catalog Schema in IEC 62769-4 which defines the XML element (simple) type “DeviceModel” and “Manufacturer”. Both types are used in (complex) element types “Protocol” and “RegDeviceType”.

As a result of the FDI® Package deployment the FDI® Package information is then present in the Information Model as specified FunctionalGroup Identification containing VendorID and DeviceID (see 5.4.3).

If a device is used as a profile device, the DeviceID returned in the scan result does not fit to the DeviceID within the GSDML. In this case, DeviceType can be used to identify the FDI® Package based on the name of the device in the FDI® Package Catalog.

The mapping between different device identification data sources is described in Table 5. Since scan results provided by the Communication Server or Gateway can convey data that is produced by the device (firmware) the device type identification mapping shall be supported by providing corresponding data in the FDI® Device Package contained Catalog and Information Model.

**Table 5 – Device identification information mapping**

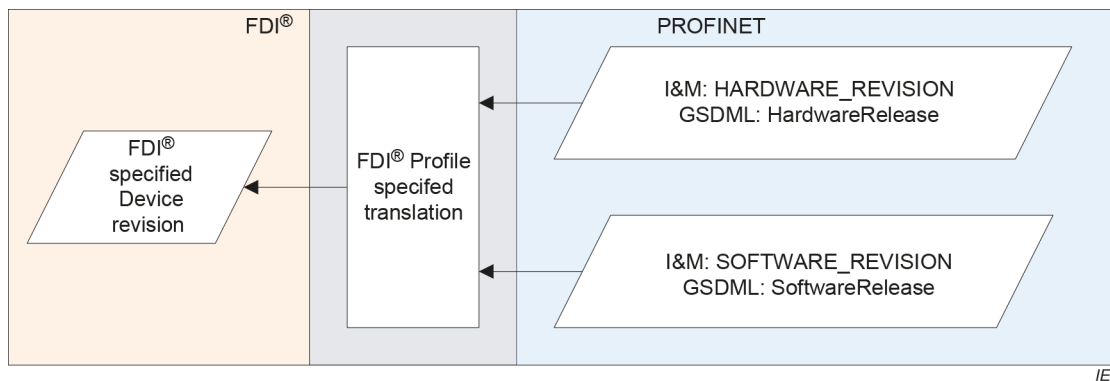
FDI® Device Package	Information Model	Communication Server provided scan result	Gateway provided scan result
Catalog specified type Manufacturer	FunctionalGroup: Identification Browse Name: VendorID	Element (path): ConnectionPoint/Identification Attribute: VendorID	COLLECTION ConnectionPoint. Identification.VendorID
Catalog specified type DeviceModel	FunctionalGroup: Identification Browse Name: DeviceID	Element (path): ConnectionPoint/Identification Attribute: DeviceID	COLLECTION ConnectionPoint. Identification.DeviceID

**5.3.2 Device type revision mapping**

IEC 62769-4 envisions a concept that allows determining the compatibility between an FDI® Device Package and a Device. IEC 62769-4 specifies a life cycle management process bearing on a single version information provided for the entire device.

PROFINET IO related specifications, for example PI Order No.: 2.352:2011 (GSDML) and PI Order No.: 3.502 (I&M), split the device revision into software and hardware related information. These specifications do not outline any rules whether the GSD, GSDML or I&M specified HARDWARE\_REVISION is independent from SOFTWARE\_REVISION.

The goal of 5.3.2 is to describe the translation rules between the PROFINET IO related specifications describing their way of providing version information and the IEC 62769-4 specified way of containing version information that can be compared against the version read from the device. The purpose is to determine compatibility between an FDI® Device Package and a Device. (Figure 1 depicts the problem).



**Figure 1 – Version mapping problem**

The firmware of a device implements the data exchange interface which shall be described by means of the FDI® Device Package content (EDD). A device firmware that implements the GSD, GSDML or I&M profile enables reading the values SOFTWARE\_REVISION and

HARDWARE\_REVISION. The access to these values shall be described in the FDI® Device Package contained EDD.

Firmware modifications that affect the firmware implemented data exchange interface shall be reflected in the FDI® Device Package. Such firmware and device description modification shall be visible in the SOFTWARE\_REVISION.

Hardware related modifications shall be captured in the HARDWARE\_REVISION value. Hardware related modifications do not necessarily require always a firmware update. Thus HARDWARE\_REVISION cannot be used to determine compatibility between a device and the FDI® Device Package. But if a hardware modification requires firmware modifications both HARDWARE\_REVISION and SOFTWARE\_REVISION shall be changed.

The IEC 62769-4 specifies the Catalog schema and an element DeviceVersion which is used in the element type declaration ListOfSupportedDeviceVersions. The value of DeviceVersion shall be compared to the device provided SOFTWARE\_REVISION in order to determine the compatibility between an FDI® Device Package and a Device.

The data format for the SOFTWARE\_REVISION is a string while the DeviceVersion expects three numbers for major, minor, and revision. Therefore the following rules apply: If the string has the format <integer>.<integer>.<integer> this is transferred to major, minor, and revision (in the same order). <integer> references to simple integer number in the string such as '1' or '12', not to other representations such as hexadecimal format (e.g. 0x001A). If <integer>.<integer> is provided, this is transferred to major and minor and '0' is used for revision. If only an <integer> is provided, this is transferred to major and '0' is used for minor and revision. A leading character or a leading character and whitespace shall be ignored. For a string in any other format the revision number shall not be considered to select the correct FDI® package.

**5.4 Information Model mapping**

**5.4.1 ProtocolType definition**

This standard refers to IEC 61158 specified protocols as these are relevant to support the device management related use cases supported through FDI® specifications. The scope is limited to data transport from the Information Model to the device.

For example, the device address management is based on services specified in the IEC 61158 series. But since the address management service is encapsulated by the IEC 62769-7 specified SetAddress service the details of IEC 61158 specified services do not need to be known.

The protocol type Profinet\_IO shall be used to identify the PROFINET IO communication. The type Profinet\_IO is a subtype of the abstract type ProtocolType (IEC 62541-100). Table 6 specifies the attributes and their values of the Protocol type Profinet\_IO.

**Table 6 – Protocol type Profinet\_IO**

Attribute	Value				
BrowseName	Profinet_IO				
IsAbstract	False				
References	NodeClass	BrowseName	Data Type	TypeDefinition	ModellingRule
Subtype of the ProtocolType defined in IEC 62541-100.					

### 5.4.2 DeviceType mapping

The properties mapping of the DeviceType node is defined in Table 7.

**Table 7 – DeviceType Property mapping**

Property	PROFINET Mapping
SerialNumber	SERIAL_NUMBER (see Table 8)
RevisionCounter	REV_COUNTER (see Table 8)
Manufacturer	String taken from FDI <sup>®</sup> package catalog (ManufacturerName from PackageT)
Model	String taken from FDI <sup>®</sup> package catalog (Name of DeviceTypeT, which is a localized name)
DeviceRevision	Not supported
DeviceManual	Not supported
SoftwareRevision	SOFTWARE_REVISION (see Table 8)
HardwareRevision	HARDWARE_REVISION (see Table 8)

### 5.4.3 FunctionalGroup identification definition

As defined in IEC 62541-100:2015, 5.3, each device representation in the FDI<sup>®</sup> Server hosted Information Model shall contain a protocol specific FunctionalGroup named Identification. The Parameters of this FunctionalGroup are defined for PROFINET as follows:

**Table 8 – PROFINET identification type definition**

BrowseName	DataType	Mandatory/Optional
VendorID	UInt16	Mandatory
DeviceID	UInt16	Mandatory
ORDER_ID	String	Mandatory
SERIAL_NUMBER	String	Mandatory
HARDWARE_REVISION	UInt16	Mandatory
SOFTWARE_REVISION	String	Mandatory
REV_COUNTER	UInt16	Mandatory
PROFILE_ID	UInt16	Mandatory
PROFILE_SPECIFIC_TYPE	UInt16	Mandatory
IM_VERSION	ByteString	Mandatory
IM_SUPPORTED	UInt16	Mandatory
DeviceType	String	Optional

The BaseDataVariable instances shall be created from VARIABLE declarations with identifiers that correspond to the browse names listed in Table 8 except the attributes VendorID and DeviceID. The related attribute values shall be taken from the GSD file (5.2.1). The element names VendorID and DeviceID match with the attribute names defined in the GSDML specification.